

IGBT Modules

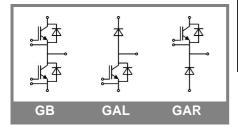
SKM 75GB123D SKM 75GAL123D SKM 75GAR123D

Features

- MOS input (voltage controlled)
- Low inductance case
- Very low tail current with low temperature dependence
- High short circuit capability, self limiting to 6 x I_{cnom}
- · Latch-up free
- Fast & soft inverse CAL diodes
- Isolated copper baseplate using DCB Direct Copper Bonding Technology
- Large clearance (10 mm) and creepage distance (20 mm)

Typical Applications*

- AC inverter drives
- UPS



Absolute Maximum Ratings T _c = 25 °C, unless otherwise specifi				
Symbol	Conditions		Values	Units
IGBT				
V_{CES}	T _j = 25 °C T _i = 150 °C		1200	V
I _C	T _j = 150 °C	T _{case} = 25 °C	75	Α
		T _{case} = 80 °C	60	Α
I _{CRM}	I _{CRM} =2xI _{Cnom}		150	Α
V_{GES}			± 20	V
t _{psc}	V_{CC} = 600 V; $V_{GE} \le 20$ V; VCES < 1200 V	T _j = 125 °C	10	μs
Inverse D	Diode			
I_{F}	T _j = 150 °C	T_{case} = 25 °C	75	Α
		T_{case} = 80 °C	50	Α
I _{FRM}	I _{FRM} =2xI _{Fnom}		150	Α
I _{FSM}	$t_p = 10 \text{ ms}; \sin.$	T _j = 150 °C	480	Α
Freewhe	eling Diode		•	
I_{F}	T _j = 150 °C	T_{case} = 25 °C	95	Α
		T _{case} = 80 °C	65	Α
I_{FRM}	I _{FRM} =2xI _{Fnom}		200	Α
I _{FSM}	t _p = 10 ms; sin	T _j = 150 °C	720	Α
Module			•	
$I_{t(RMS)}$			200	Α
T _{vj}			- 40+ 150	°C
T _{stg}			- 40+ 125	°C
V _{isol}	AC, 1 min.		2500	V

Characteristics T _c =		25 °C, unless otherwise specified				
Symbol	Conditions		min.	typ.	max.	Units
IGBT						
$V_{GE(th)}$	$V_{GE} = V_{CE}$, $I_{C} = 2 \text{ mA}$		4,5	5,5	6,5	V
I _{CES}	$V_{GE} = 0 V, V_{CE} = V_{CES}$	T _j = 25 °C T _i = 25 °C		0,1	0,3	mA
V _{CE0}		T _j = 25 °C		1,4	1,6	V
		T _j = 125 °C		1,6	1,8	V
r _{CE}	V _{GE} = 15 V	T _j = 25°C		22	28	mΩ
		T _j = 125°C		30	38	$m\Omega$
V _{CE(sat)}	I _{Cnom} = 50 A, V _{GE} = 15 V	T _j = °C _{chiplev.}		2,5	3	V
C _{ies}				3,3	4,3	nF
C _{oes}	$V_{CE} = 25, V_{GE} = 0 V$	f = 1 MHz		0,5	0,6	nF
C _{res}				0,22	0,3	nF
Q_G	V _{GE} = -8 - +20V			500		nC
R _{Gint}	$T_j = {^{\circ}C}$			5		Ω
t _{d(on)}				44	100	ns
t _r	$R_{Gon} = 22 \Omega$	V _{CC} = 600V		56	100	ns
E _{on}		I _C = 50A		8		mJ
t _{d(off)}	$R_{Goff} = 22 \Omega$	T _j = 125 °C		380	500	ns
t _f		$V_{GE} = \pm 15V$		70	100	ns
E _{off}				5		mJ
$R_{th(j-c)}$	per IGBT				0,27	K/W



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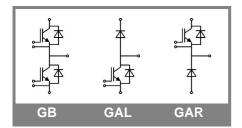
Typical Applications*

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Characte	ristics					
Symbol	Conditions		min.	typ.	max.	Units
Inverse D	Diode					•
$V_F = V_{EC}$	I_{Fnom} = 50 A; V_{GE} = 0 V	$T_j = 25 ^{\circ}C_{\text{chiplev.}}$		2	2,5	V
		$T_j = 125 ^{\circ}C_{\text{chiplev.}}$		1,8		V
V _{F0}		T _j = 25 °C		1,1	1,2	V
		T _j = 125 °C				V
r_F		T _j = 25 °C		18	26	mΩ
		T _j = 125 °C T _j = 125 °C				mΩ
I _{RRM}	I _F = 50 A	T _j = 125 °C		35		A
Q _{rr}	di/dt = 800 A/µs					μC
E _{rr}	V _{GE} = 0 V; V _{CC} = 600 V					mJ
$R_{th(j-c)D}$	per diode				0,6	K/W
	eling Diode					
$V_F = V_{EC}$	I_{Fnom} = 50 A; V_{GE} = 0 V			1,85	2,2	V
		$T_j = 125 ^{\circ}\text{C}_{\text{chiplev.}}$ $T_j = 25 ^{\circ}\text{C}$		1,6		V
V _{F0}		T _j = 25 °C		1,1	1,2	V
		$T_j = 125 ^{\circ}\text{C}$ $T_j = 25 ^{\circ}\text{C}$				V
r _F				15	20	V
		T _j = 125 °C				V
I _{RRM}	I _F = 50 A	T _j = 125 °C		40		A
Q _{rr}	\\ - 0\\\\\ - 000\\					μC
E _{rr}	V _{GE} = 0 V; V _{CC} = 600 V					mJ
$R_{th(j-c)FD}$	per diode				0,5	K/W
Module						
L _{CE}					30	nΗ
R _{CC'+EE'}	res., terminal-chip	T _{case} = 25 °C		0,75		mΩ
		T _{case} = 125 °C		1		mΩ
R _{th(c-s)}	per module			-	0,05	K/W
M_s	to heat sink M6		3		5	Nm
M_t	to terminals M5		2,5		5	Nm
w					160	g

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.





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Features

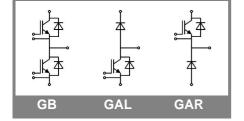
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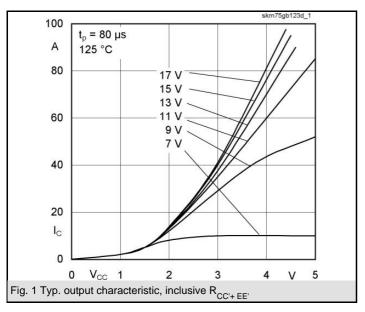
Typical Applications*

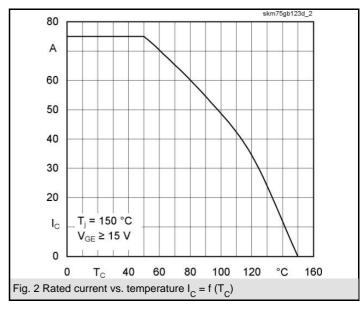
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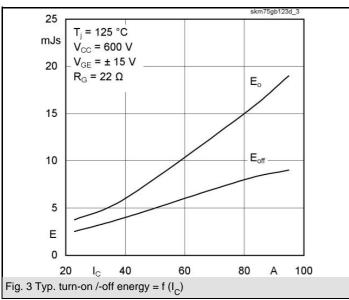
Z _{th} Symbol	Conditions	Values	Units
	Conditions	Values	Oilles
Z _{th(j-c)l}	i = 1	180	mk/W
r _i	i = 1 i = 2	64	mk/W
R _i	i = 2 i = 3	22	mk/W
R _i	i = 4	4	mk/W
R _i	i = 4 i = 1	•	
tau _i	i = 1 i = 2	0,0327 0,0479	S
tau _i			S
tau _i	i = 3	0,008	S
tau _i	i = 4	0,005	S
Z _{th(j-c)D}		·	
R _i tn(J-C)D	i = 1	380	mk/W
R _i	i = 2	190	mk/W
R _i	i = 3	26	mk/W
R _i	i = 4	4	mk/W
tau _i	i = 1	0,0947	s
tau _i	i = 2	0,006	s
tau _i	i = 3	0,08	s
tau _i	i = 4	0,003	s

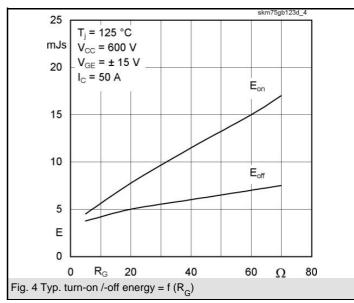
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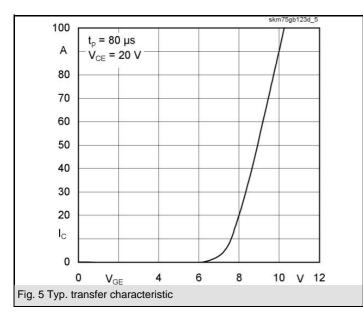


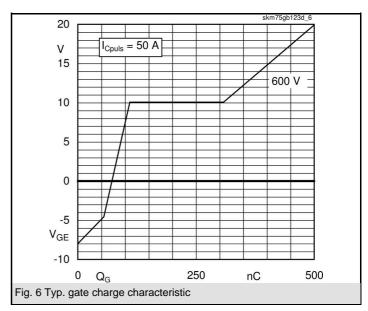


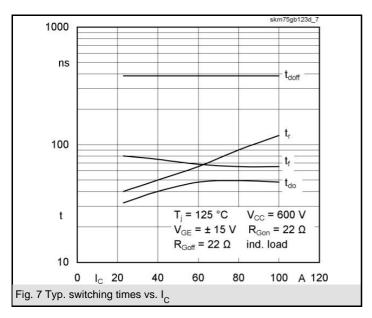


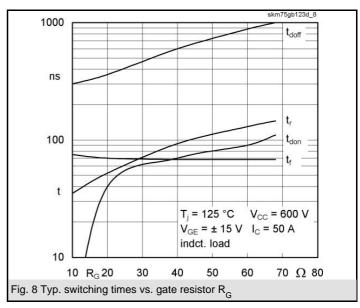


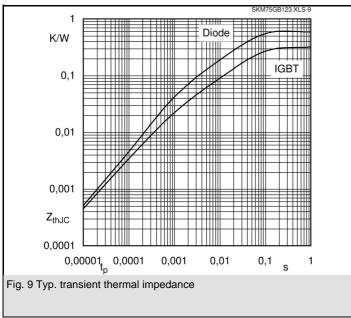


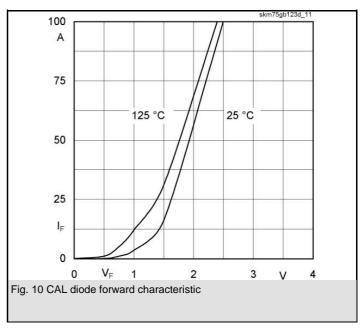


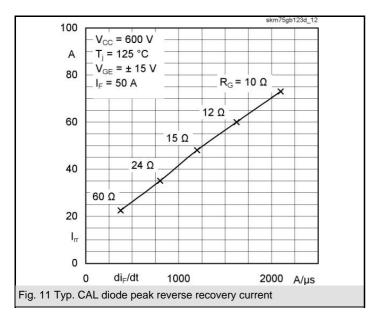


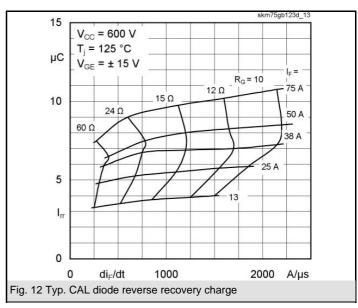






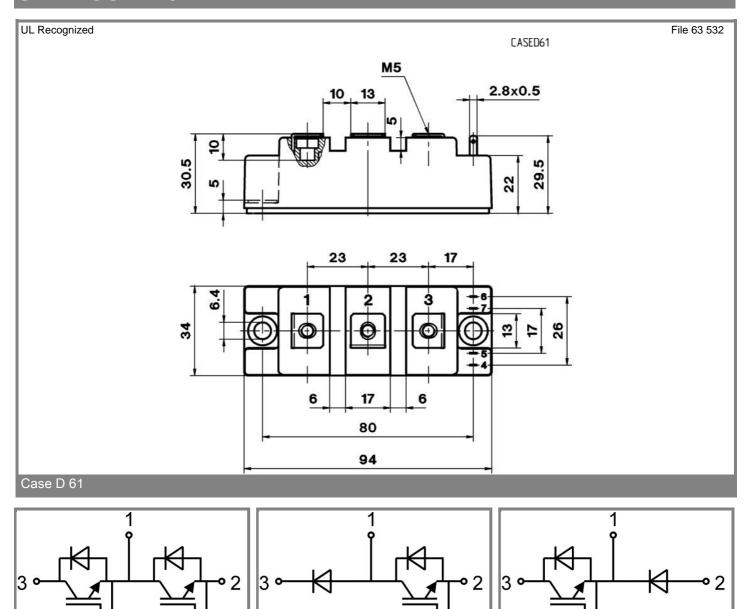






Case D 61

GAL



Case D 62 (→ D 61)

GAR

Case D 63 (→ D 61)